

GX76470

4x64Gbit/s Linear Differential I/O Driver

The GX76470 is a low-power, high-performance, quad-channel linear driver chip. It is designed for 400G/600G optical integrated transmitter small form factor (SFF) modules for metro and long-haul applications. The GX76470 integrated quad lanes of driver with SPI circuitry for DC controls on a single die. Each channel of driver has 100Ω differential AC-coupled input and 55Ω differential DC-coupled output, and linear output voltage of 2.8V_{ppd} suitable for InP and SiP multi-level modulations.

Applications

- 400/600Gbps 16QAM/64QAM advanced multi-level modulation systems
- High bandwidth SFF optical integrated modules

Features

- Data rate up to 64Gbps per channel for 400G/600G DP-mQAM applications
- > 40GHz Bandwidth
- > 10dB dynamic range of gain control
- 0.55W (typical) per channel at linear 2.8 V_{ppd}
- AC-coupled 100Ω differential input/DC-coupled 55Ω differential output
- Ultra-low inter-channel cross-talk
- Peaking adjustment functionality
- Analog control for gain and output voltage setting, and analog monitor for peak detector and gain control monitor
- OIF compliant SPI digital interface integration

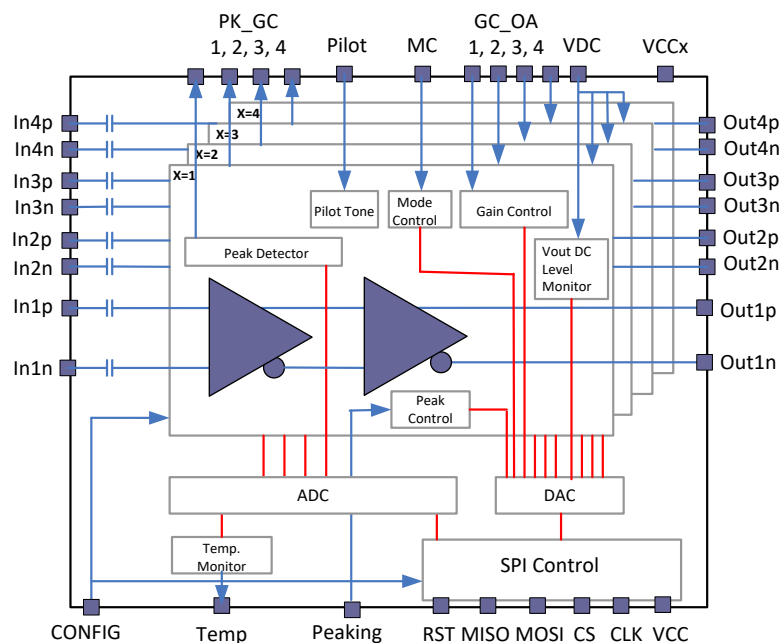


Figure 1. Block Diagram

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